

ORDERING INFORMATION

PART IDENTIFIER: SMT2010A

ASSEMBLY DWG: 1101684

SPECIFICATIONS

1. ELECTRICAL:

Impedance:	50 Ω Nominal.
Frequency:	DC - 3 GHz.
VSWR:	1.25:1 Max.
Input Power:	10 Watts. Chip Soldered to Mounting Surface. Mounting Surface Temperature Maintained At 100°C Maximum. Apply Linear De-Rating of Input Power To 0 Watts At 150°C.

2. ENVIRONMENTAL:

Non-Operating:	-55°C To +150°C.
Operating:	-55°C To +150°C.

3. MARKING:

Unit Marking:	None.
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4. QUALITY ASSURANCE:

Sample Inspect Per ANSI/ASQC Z1.4 General Inspection, Level II, AQL = 1.0.

Visual And Mechanical Per 824W154.

Dc Resistance: 50 Ω \pm 5 %.

Data Requirements:

No Test Data Required for Customer.

Data Retention – 24 Months.

5. PACKAGING:

Standard Packaging:	Standard Pack Per 755W002.
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6. MECHANICAL:

Workmanship:	Per MIL-PRF-55342.
Substrate:	Alumina, MIL-I-10.
Terminal & Ground Plane:	Thick Film, Nickel Barrier, Solder Plated.
Resist:	Thick Film.

Thermal Impedance (R θ):

2.500°C / Watt R θ From Resist Film to Mounting Surface Directly Under Center of Chip. Chip Soldered Directly to Mounting Surface.

Film Temperature (T_f):

200°C Absolute Maximum Film Temperature. De-Rate To 150°C Maximum Film Temperature for All Military/High-Reliability Applications.

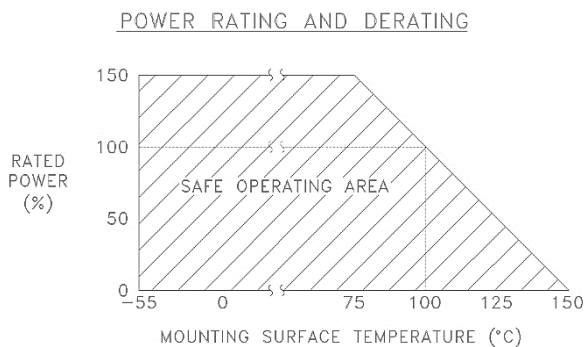
Thermal:

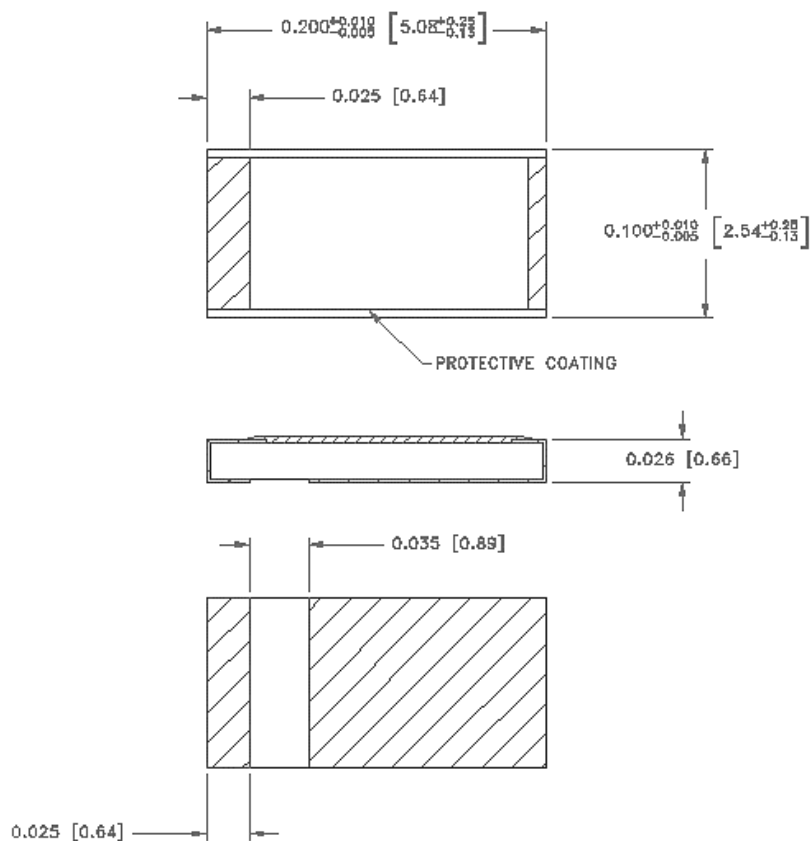
Determine Maximum Mounting Surface Temperature by Applying the Following Formula:

$$T_s = T_f - (P_{\max} \times R_{\theta})$$

Where:

T _s	=	Maximum Mounting Surface Temperature
T _f	=	Maximum Film Temperature
P _{max}	=	Maximum Applied Input Power
R θ	=	Chip Thermal Impedance.





Unless Otherwise Specified:

Tolerance: X.XXX = ± 0.005.

Metric equivalents given in [mm] are for reference information only.